

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6976251

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ANANTHA K. SUBRAMANI	01/07/2015
DEEPAK JADHAV	11/17/2014
ASHISH GOEL	01/26/2015
HANBING WU	01/07/2015
PRASHANTH KOTHNUR	01/07/2015
CHI HONG CHING	01/07/2015
RECEIVING PARTY DATA	
Name:	APPLIED MATERIALS, INC.
Street Address:	3050 BOWERS AVENUE
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17503994
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7328150404
Email:	slewis@dsiplaw.com
Correspondent Name:	SERVILLA WHITNEY LLC
Address Line 1:	33 WOOD AVENUE SOUTH, SUITE 830
Address Line 4:	ISELIN, NEW JERSEY 08830
ATTORNEY DOCKET NUMBER:	01735901DIV
NAME OF SUBMITTER:	SCOTT S. SERVILLA
SIGNATURE:	/Scott S. Servilla, Reg. No. 40806/
DATE SIGNED:	10/19/2021
Total Attachments: 3	

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PATENT

REEL: 057833 FRAME: 0666

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

DEPOSITION SYSTEM WITH MULTI-CATHODE AND METHOD OF MANUFACTURE THEREOF

for which a United States patent application has been executed on or before the date of this assignment;


WHEREAS, Applied Materials, Inc., a Corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries.

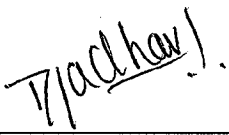
NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee(s), the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee(s), the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee(s) where said Assignee(s) may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee(s).
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee(s), its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

5. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number of the application in the spaces that follow:

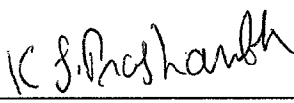
Serial Number: 14/606,367 Filing Date: January 27, 2015


Signature:  Date: Jan 7th 2015.
Anantha K. Subramani

Signature:  Date: 17th November-2014
Deepak Jadhav

Signature: _____ Date: _____
Ashish Goel

Signature:  Date: 1-7-15
Hanbing Wu

Signature:  Date: 1-7-15
Prashanth Kothnur

Signature:  Date: 1-7-2015
Chi Hong Ching

5. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number of the application in the spaces that follow:

Serial Number: 14/606,367 Filing Date: January 27, 2015

Signature: _____ Date: _____
Anantha K. Subramani

Signature: _____ Date: _____
Deepak Jadhav

Signature:  _____ Date: Jan 26, 2015
Ashish Goel

Signature: _____ Date: _____
Hanbing Wu

Signature: _____ Date: _____
Prashanth Kothnur

Signature: _____ Date: _____
Chi Hong Ching